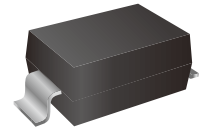


Surface Mount Superfast Recovery Rectifier

Features

- Super fast switching for high efficiency
- Glass passivated chip junction
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SMAW
- Terminal: Leads solderable per MIL-STD-750 Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any

Ordering Information

Part Number	Shipping	Reel
LTE2AW THRU LTE2JW	8000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	LTE2AW	LTE2BW	LTE2CW	LTE2DW	LTE2EW	LTE2GW	LTE2JW	Unit
	Marking	E2AW	E2BW	E2CW	E2DW	E2EW	E2GW	E2JW	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$	2							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A
Maximum instantaneous forward voltage at 2A	V_F	0.95			1.25		1.7		V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	5			100				μA
Maximum reverse recovery time (Note1)	T_{RR}	35							ns
Typical Junction Capacitance (Note2)	C_J	40							pF
Typical thermal resistance (Note3)	$R_{\theta JA}$	60							$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

Note: (1) Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$.
 (2) Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 (3) P.C.B. mounted with 1" x 1" (2.54cm x 2.54cm) copper pad areas.



Ratings and Characteristics Curves

FIG. 1 FORWARD CURRENT DERATING CURVE

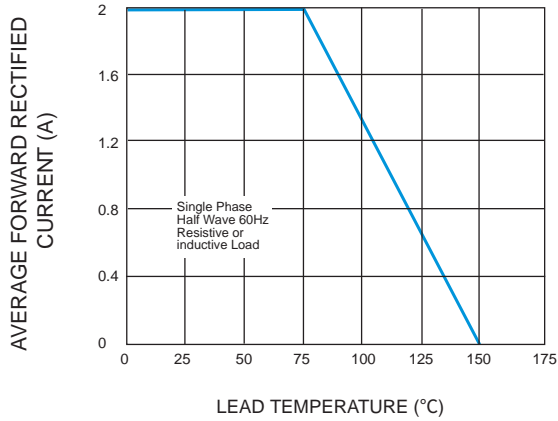


FIG. 2 MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

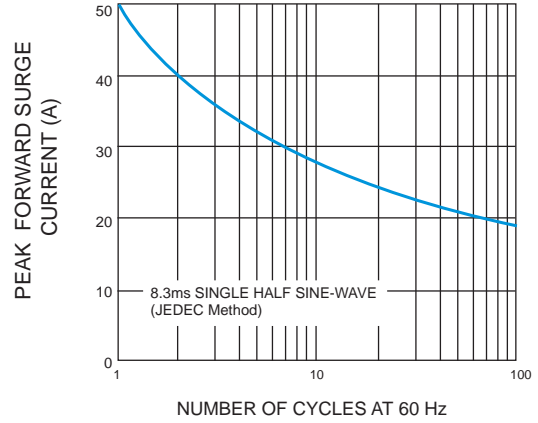


FIG. 3 TYPICAL FORWARD CHARACTERISTICS

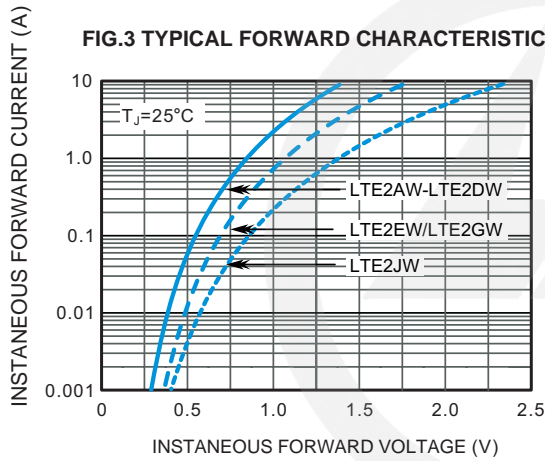


FIG. 4 TYPICAL REVERSE CHARACTERISTICS

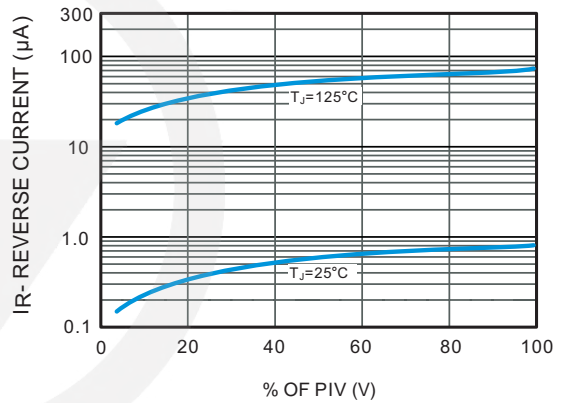
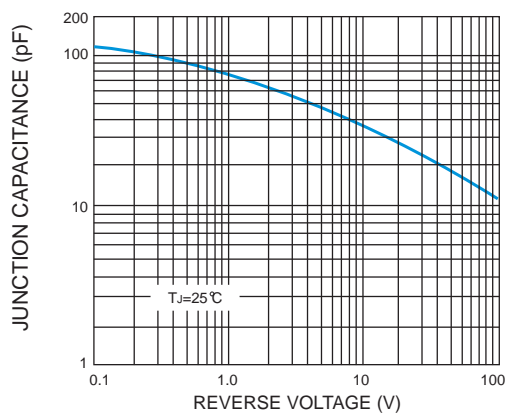
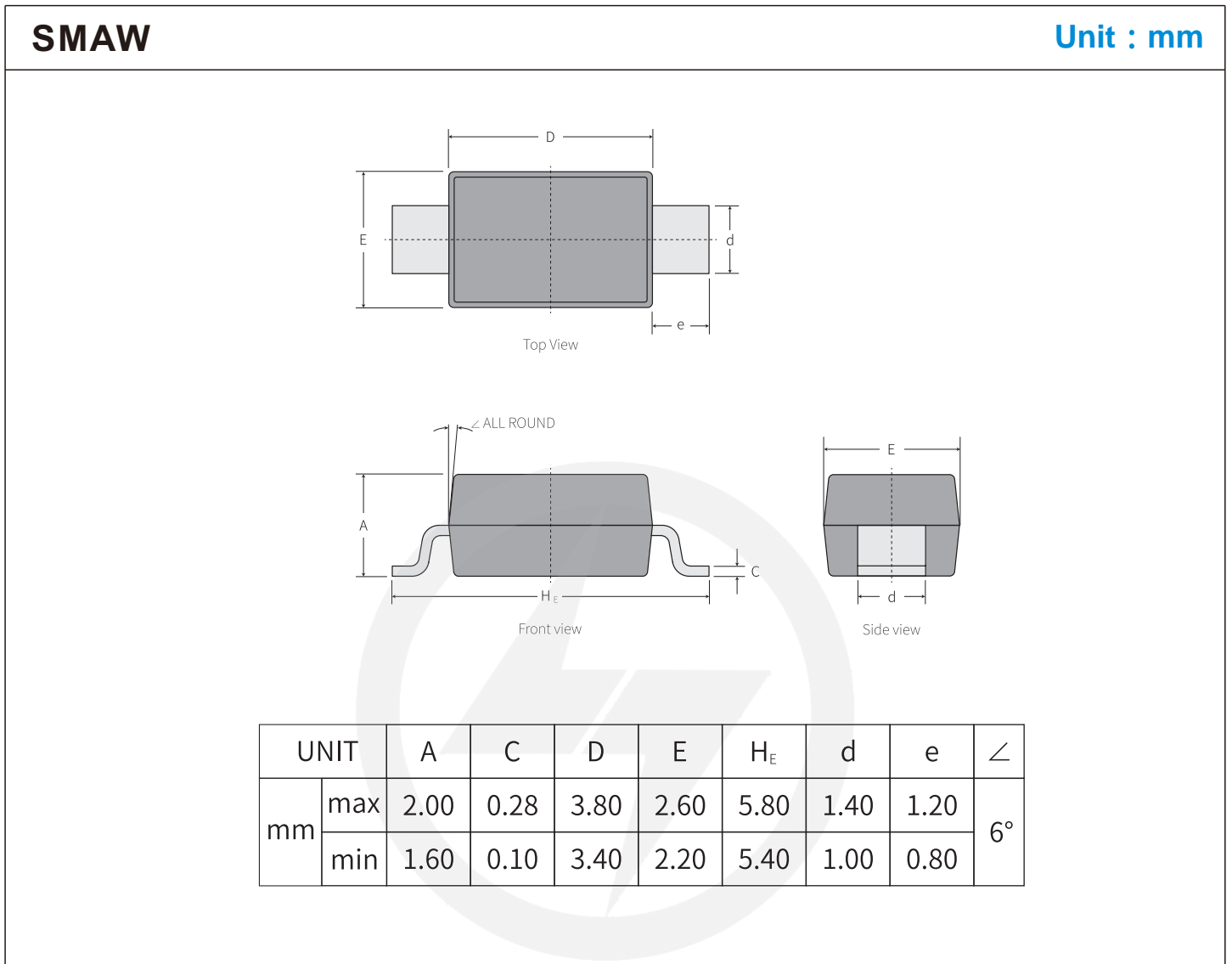


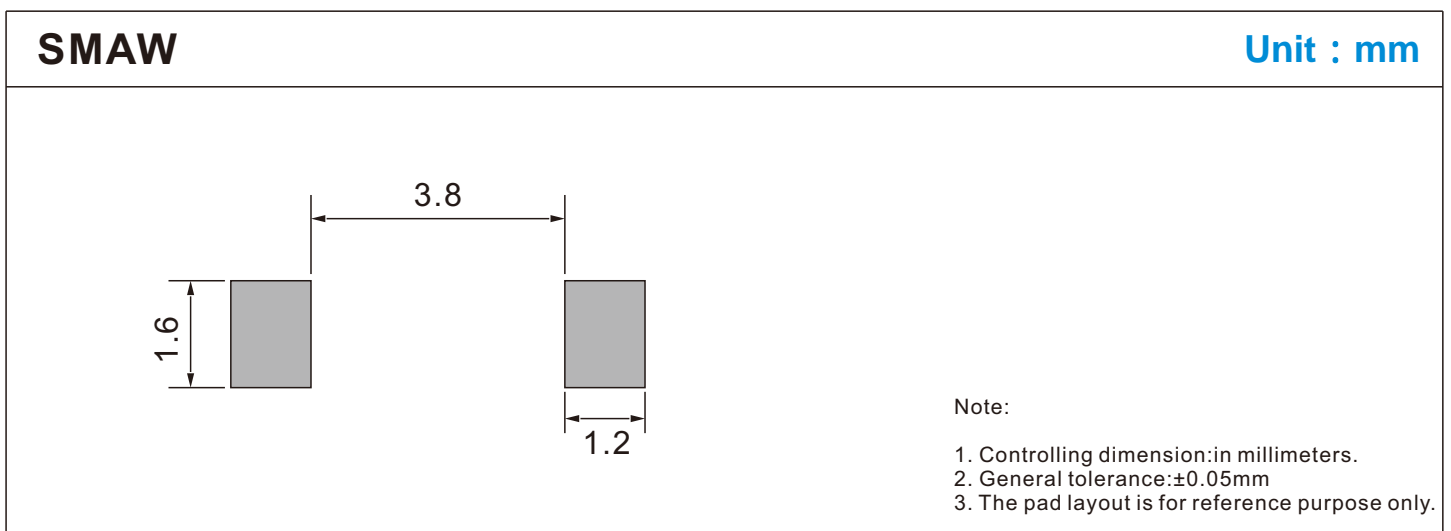
FIG. 5 TYPICAL JUNCTION CAPACITANCE



Package Outline

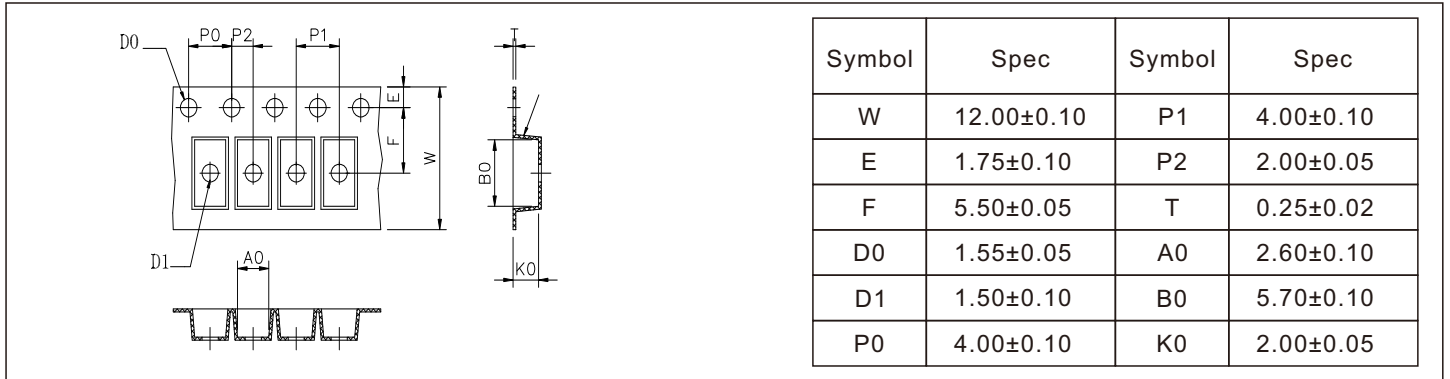


Suggested Pad Layout



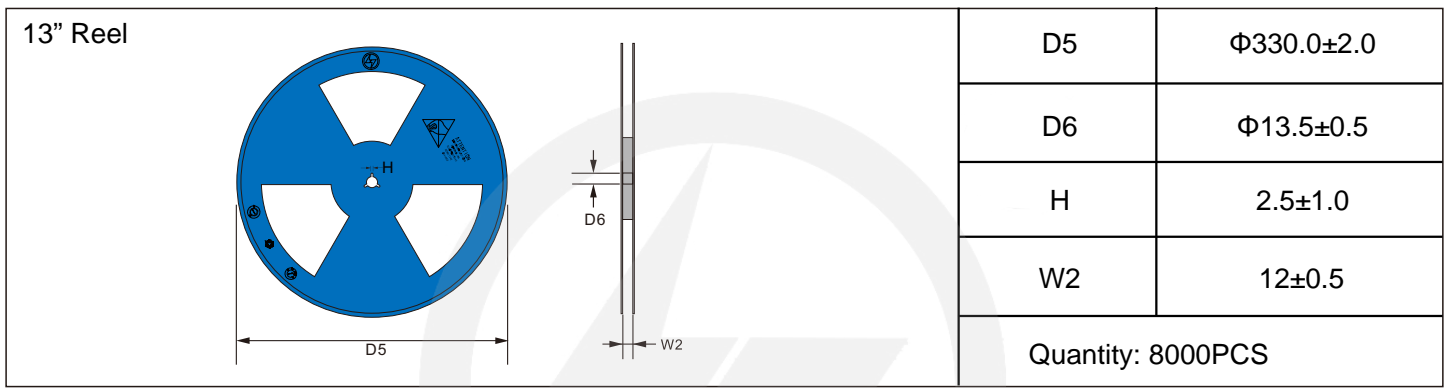
Carrier Tape Dimensions

Unit : mm

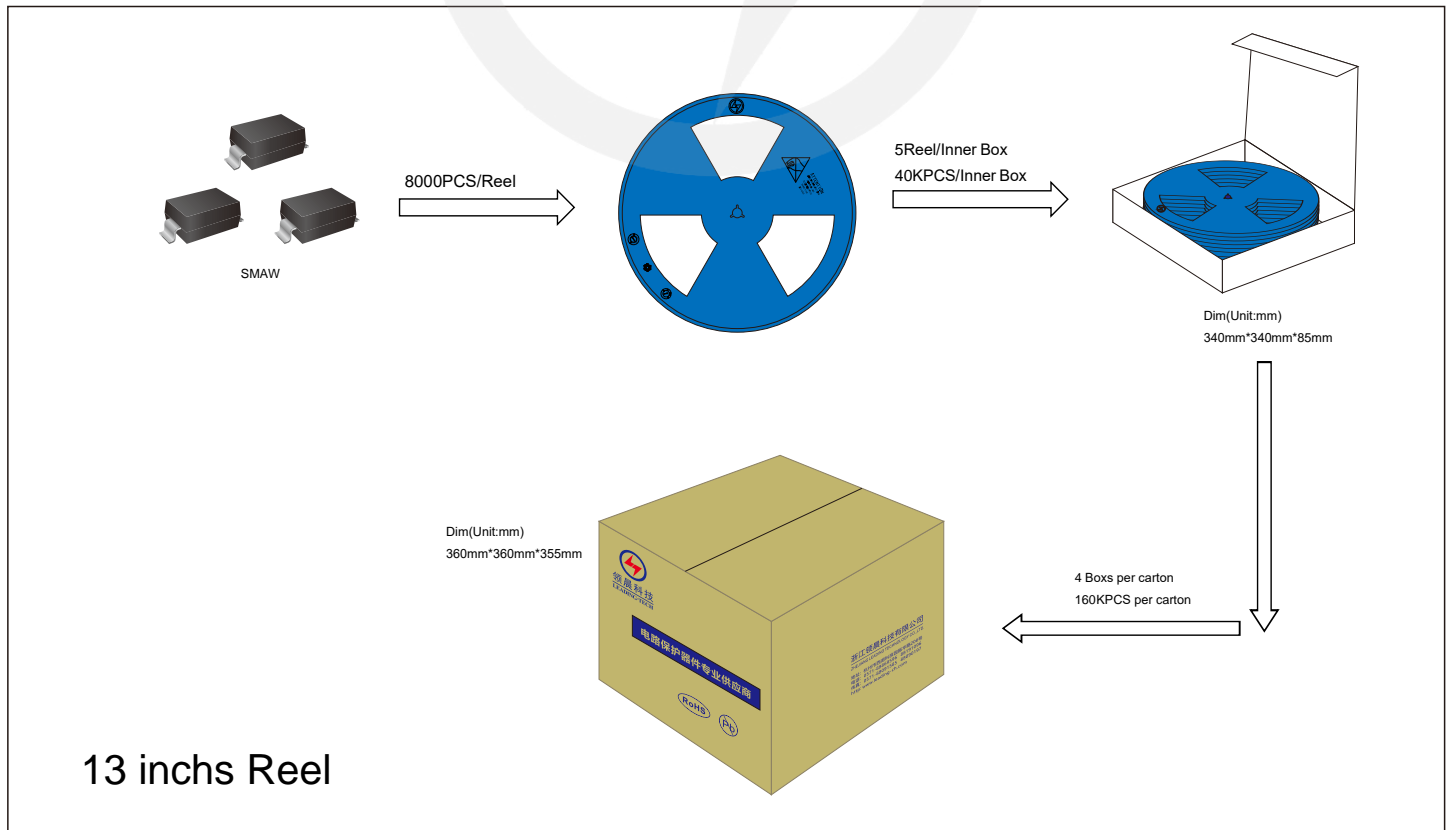


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2023.11.30	2023.11.30	1.0	New File	/	Ding	
02	2025.06.27	2025.06.27	1.1	Update packaging information	/	Ding	